

SOD124

transfer-moulded thermo-setting plastic small rectangular
surface mounted package; 2 connectors

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SOD2
Package type industry code	SOD2
Package style descriptive code	SOD (small outline diode)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	DO-214AC
Mounting method type	S (surface mount)
Issue date	16-3-2006

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		4.3	-	4.4	4.5	mm
E	package width		2.4	-	2.6	2.8	mm
A	seated height		2	-	2.15	2.3	mm
n ₂	actual quantity of termination		-	-	2	-	



2. Package outline

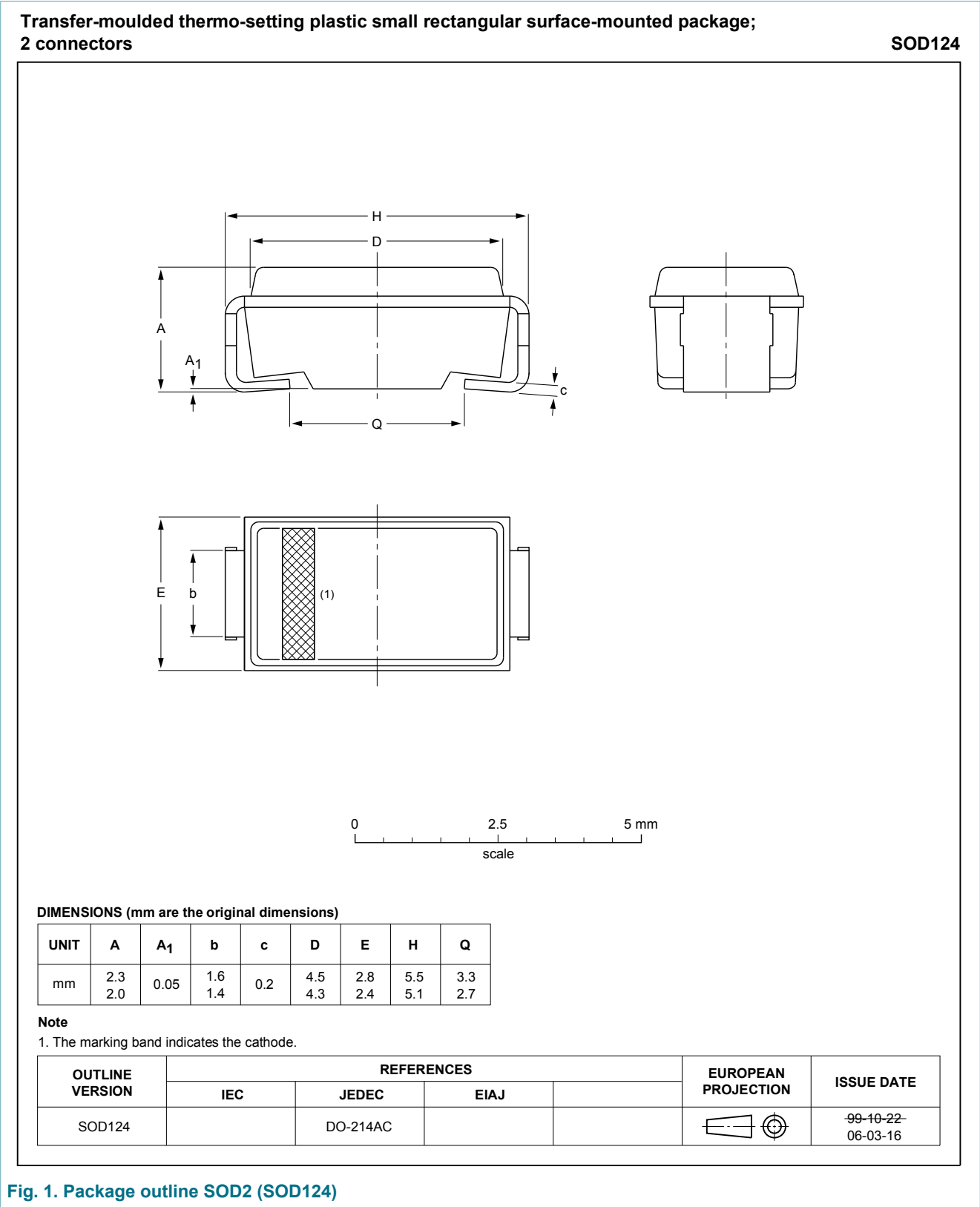


Fig. 1. Package outline SOD2 (SOD124)

3. Legal information

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Date of release: 8 February 2016